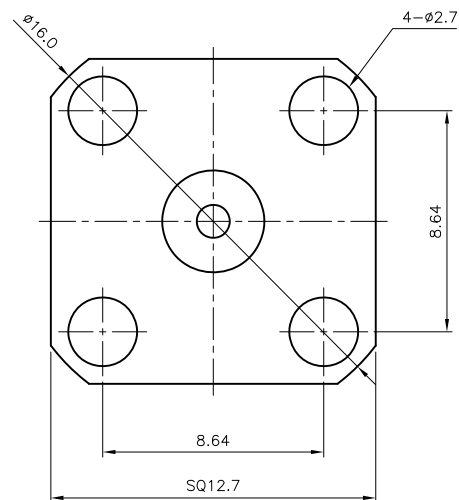
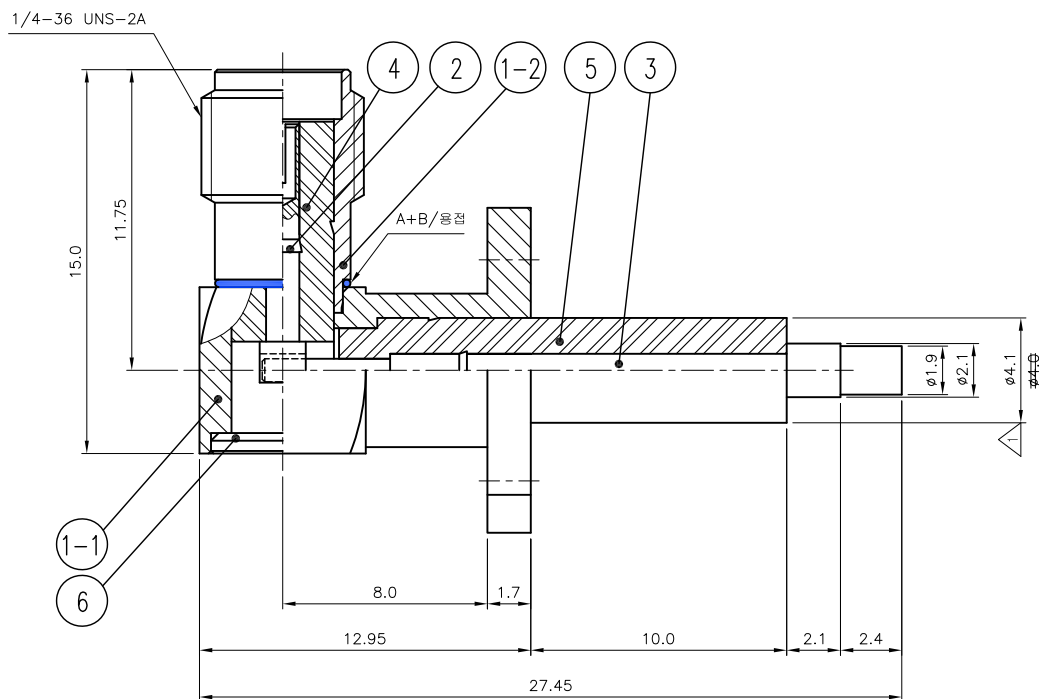


REVISION					
REV	DESCRIPTION	DRAWN	APPR	DATE	
1	Initial Registration	I.C.KIM		2019.09.26.	
1	[설번No.202104-0003] 바디 PUNCH -> HOOK 변경 및 A+B/용접 구조 적용	S.Y.EUN	I.C.KIM	2021.04.09.	
2	바디 용접화로 인한 코드 변경	S.Y.EUN	I.C.KIM	2021.07.06.	
3	PIN STEP 추가	K.S.KIM	S.L.SON	2021.11.05.	



6	COVER	1	MBsBD C3604BD-F	Gold Plate	DCO00038-5/1
5	INSULATOR	1	TEFLON		DIN03087-N/2
4	INSULATOR	1	TEFLON		DIN03087-N/1
3	CONTACT	1	MBsBD C3604BD-F	Gold Plate	DCT04065-5/2
2	CONTACT	1	BeCu C17300	Gold Plate	DCT00151-5/1
1-2	BODY (B)	1	MBsBD C3604BD-F	Gold Plate	DBD02134-1/3
1-1	BODY (A)	1	MBsBD C3604BD-F	Gold Plate	DBD02134-1/2

NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE
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TOLERANCE	Decimal ±0.3	DATE	2021. 11. 05		 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017 KJ COMTECH CO.,LTD.
	Angle ±1°	APPROVED BY	S.L.SON		
MATERIAL	_____	CHECKED BY			TITLE SMA50 PCB JL-4R
	_____	DRAWN BY	K.S.KIM		
FINISH	_____	SCALE	4/1	UNIT	A3 DWG NO. CN01342-7/6 REVISION 6 SHEET 1 of 1
	_____			mm 	